



Attorney Docket no: 0553-0193.01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayama et al.

Serial No.: 10/672,521

Filed: September 26, 2003

For: Wiring Material, Semiconductor Device
Provided With A Wiring Using The Wiring
Material And Method of Manufacturing
Thereof

Examiner: Ha T. Nguyen

Art Unit: 2812

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

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Shannon Wallace

Name of applicant, assignee, or Registered Rep.

Shannon Wallace 12/2/05
Signature Date

AMENDMENT D (AFTER FINAL)

In response to the Final Rejection of August 9, 2005 and the Advisory Action of November 22, 2005, a RCE and one month extension of time being submitted herewith, please amend the above-identified application as follows: